

Please replace the abstract on page 21 with the following new abstract:

The present invention provides a method for fabricating semiconductor circuit modules having the following steps: application of a patterned connection layer to a transfer substrate, application of active circuit devices and / or passive circuit devices with contact areas pointing toward the patterned connection layer, connection of the circuit devices to one another by means of a filler at least between the circuit devices, removal of the transfer substrate, and application of electrical connection devices for selective contact connection of the contact area of the circuit devices to one another.